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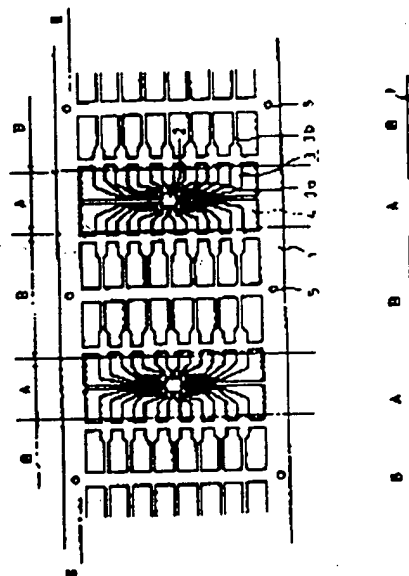
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(54) LEAD FRAME AND SEMICONDUCTOR DEVICE USING THE SAME

(57)Abstract:

PURPOSE: To enhance the strength of an external connector in a lead frame of a resin molded semiconductor device and increase the density of a chip connector by forming thin chip carrying base of the lead frame and thin lead terminal formed therearound and thick external connecting lead terminal.

CONSTITUTION: A guide hole 5 is perforated at a metallic plate, and thin and thick portions A and B are formed by pressing. Then, a chip carrying base 2 and a lead terminal 3 are formed on the lead frame 1 by stamping. The semiconductor chip is carried on a chip carrying base 2, wire bonded to the lead terminal 3, and clamped from both front and rear surfaces of the molding frame, resin is filled to seal the semiconductor device.



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Abstract

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